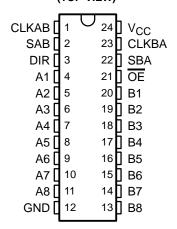
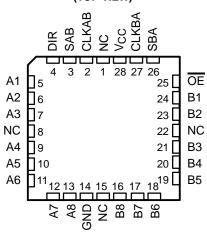
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I<sub>CC</sub>
- Typical t<sub>pd</sub> = 11 ns

SN54HC646 ... JT OR W PACKAGE SN74HC646 ... DW OR NT PACKAGE (TOP VIEW)



- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Independent Registers for A and B Buses
- Multiplexed Real-Time and Stored Data
- True Data Paths

SN54HC646 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

### description/ordering information

The 'HC646 devices consist of bus-transceiver circuits with 3-state outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'HC646 devices.

Output-enable ( $\overline{OE}$ ) and direction-control (DIR) inputs control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either or both registers.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. DIR determines which bus receives data when  $\overline{OE}$  is active (low). In the isolation mode ( $\overline{OE}$  high), A data may be stored in one register and/or B data may be stored in the other register.

### ORDERING INFORMATION

TA	PACKAC	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – NT	Tube	SN74HC646NT	SN74HC646NT
–40°C to 85°C	SOIC - DW	Tube	SN74HC646DW	HC646
	SOIC - DW	Tape and reel	SN74HC646DWR	ПС040
	CDIP – JT	Tube	SNJ54HC646JT	SNJ54HC646JT
–55°C to 125°C	CFP – W	Tube	SNJ54HC646W	SNJ54HC646W
	LCCC – FK	Tube	SNJ54HC646FK	SNJ54HC646FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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### SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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### description/ordering information (continued)

To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

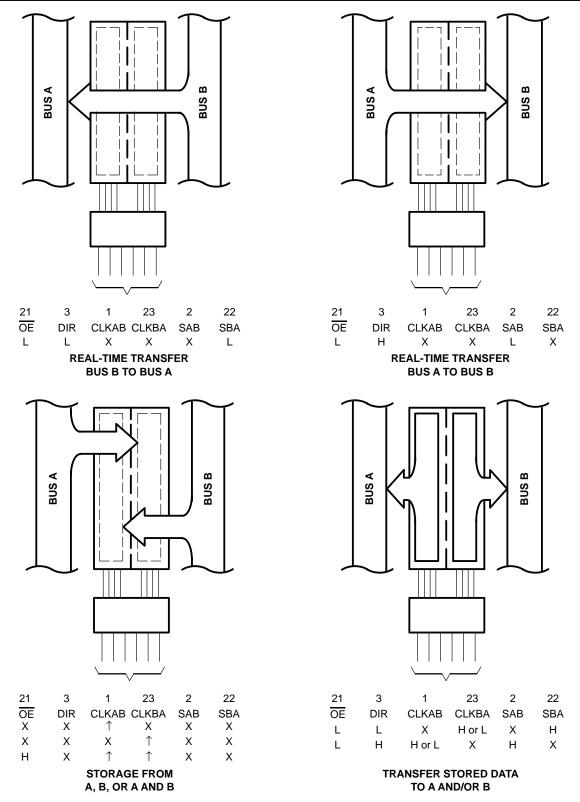
When an output function is disabled, the input function is still enabled and can be used to store data. Only one of the two buses, A or B, may be driven at a time.

#### **FUNCTION TABLE**

		INP	UTS			DAT	A I/O	OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Х	Х	Х	Input	Unspecified†	Store A, B unspecified <sup>†</sup>
Х	Χ	Χ	$\uparrow$	X	Χ	Unspecified <sup>†</sup>	Input	Store B, A unspecified <sup>†</sup>
Н	Х	1	1	Х	Х	Input	Input	Store A and B data
Н	Χ	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Χ	Х	L	Output	Input	Real-time B data to A bus
L	L	Х	H or L	Χ	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
L	Н	H or L	X	Н	Χ	Input	Output	Stored A data to B bus

The data-output functions can be enabled or disabled by various signals at  $\overline{\text{OE}}$  and DIR. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



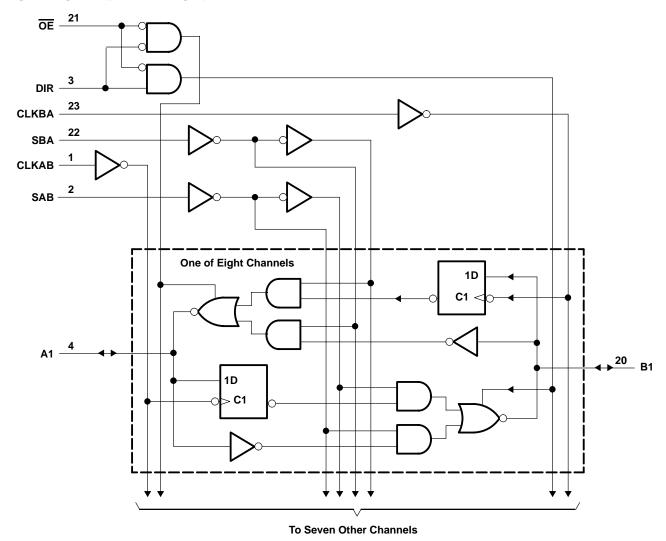


Pin numbers shown are for the DW, JT, NT, and W packages.

Figure 1. Bus-Management Functions



### logic diagram (positive logic)



Pin numbers shown are for the DW, JT, NT, and W packages.

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±20 mA
Continuous output current, I <sub>O</sub> (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±35 mA
Continuous current through V <sub>CC</sub> or GND	±70 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DW package	46°C/W
(see Note 3): NT package	67°C/W
Storage temperature range, Teta	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-3.



### recommended operating conditions (see Note 4)

			SN	154HC64	16	SN	174HC64	6	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
٧ıH	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			V
		VCC = 6 V	4.2		7	4.2			
		V <sub>CC</sub> = 2 V		Ş	0.5			0.5	
٧ <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 4.5 V		1.35				1.35	V
		VCC = 6 V		5	1.8			1.8	
٧ <sub>I</sub>	Input voltage		0 2	5	VCC	0		VCC	V
٧o	Output voltage		0	)	VCC	0		VCC	V
		V <sub>CC</sub> = 2 V	Q.		1000			1000	
t <sub>t</sub>	Input transition (rise and fall) time	V <sub>CC</sub> = 4.5 V			500			500	ns
		VCC = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	AMETED	TEST OF	NUDITIONS	V	Т	A = 25°C	;	SN54F	IC646	SN74F	IC646	UNIT
PAR	AMETER	lesi co	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	ONIT
				2 V	1.9	1.998		1.9		1.9		
			$I_{OH} = -20  \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Vон		$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V
			$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7	7	3.84		
			$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2	1/5	5.34		
				2 V		0.002	0.1		0.1		0.1	
		VI = VIH or VIL	$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
VOL				6 V		0.001	0.1	3	0.1		0.1	V
			$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26	90	0.4		0.33	
			$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26	y <sub>d</sub>	0.4		0.33	
lį	Control inputs	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	A or B	VO = VCC or 0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc		$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci	Control inputs			2 V to 6 V		3	10		10		10	pF

## SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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# timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V	T <sub>A</sub> = :	25°C	SN54F	IC646	SN74H	IC646	LINIT
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V		6		4.3		5.5	
fclock	Clock frequency	4.5 V		31		22		27	MHz
		6 V		36		25		31	
		2 V	80		115	15	95		
$t_W$	Pulse duration, CLKBA or CLKAB high or low	4.5 V	16		23	EL	19		ns
		6 V	14		20	2	16		
		2 V	100		150	,	125		
t <sub>su</sub>	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5 V	20		30		25		ns
		6 V	17		26		21		
		2 V	5		5		5		
th	Hold time, A after CLKAB↑ or B after CLKBA↑		5		5		5		ns
		6 V	5		5		5		



# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

DADAMETER	FROM	то	V	T,	Δ = 25°C	;	SN54H	IC646	SN74H	C646	UNIT
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
			2 V	6	11		4.4		5.5		
f <sub>max</sub>			4.5 V	31	54		22		27		MHz
			6 V	36	64		25		31		
			2 V		65	180		270		225	
	CLKBA or CLKAB	A or B	4.5 V		18	36		54		45	
			6 V		14	31		46		38	
			2 V		50	135		205		170	
t <sub>pd</sub>	A or B	B or A	4.5 V		14	27		41		34	ns
			6 V		11	23		35		29	
			2 V		70	190		285		240	
	SBA or SAB†	A or B	4.5 V		20	38		57		48	
			6 V		16	32		48		41	
			2 V		85	245	7	370		305	
t <sub>en</sub>	ŌĒ	A or B	4.5 V		25	49	0/2/	74		61	ns
			6 V		20	42	70	63		52	
			2 V		85	245	d	370		305	
<sup>t</sup> dis	ŌĒ	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		80	245		370		305	
t <sub>en</sub>	DIR	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		80	245		370		305	
<sup>t</sup> dis	DIR	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		28	60		90		75	
t <sub>t</sub>		Any	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

# SN54HC646, SN74HC646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCLS150C - DECEMBER 1982 - REVISED MARCH 2003

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 150 pF (unless otherwise noted) (see Figure 2)

DADAMETED	FROM	то	V	TΔ	= 25°C	;	SN54F	IC646	SN74H	C646	LINIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		90	265		400		330	
	CLKBA or CLKAB	A or B	4.5 V		24	53		80		66	
			6 V		20	46		68		57	
			2 V		70	220		335		280	
<sup>t</sup> pd	A or B	B or A	4.5 V		20	44		67		56	ns
			6 V		15	38		57		49	
	SBA or SAB†		2 V		80	275		415		345	
		A or B	4.5 V		24	55	4	83		69	
			6 V		20	47	Č,	70		60	
			2 V		113	330	$g_{Q_i}$	500		410	
	ŌĒ	A or B	4.5 V		33	66	) Jy	100		82	
			6 V		27	57		85		71	
t <sub>en</sub>			2 V		113	330		500		410	ns
	DIR	A or B	4.5 V		33	66		100		82	
			6 V		27	57		85		71	
			2 V		45	210		315		265	
t <sub>t</sub>		Any	4.5 V		17	42		63		53	ns
			6 V		13	36		53		43	

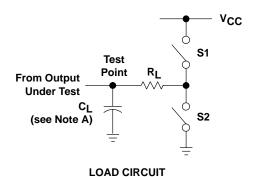
<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

# operating characteristics, $T_A = 25^{\circ}C$

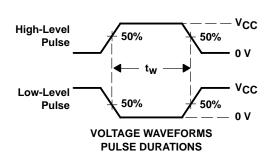
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	50	pF

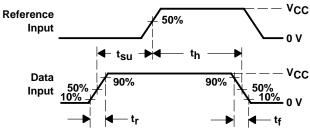


### PARAMETER MEASUREMENT INFORMATION

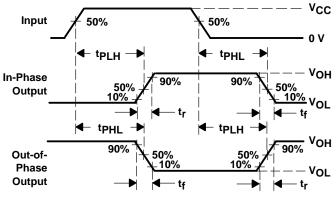


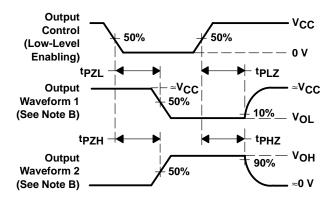
**PARAMETER**  $C_L$ S1 S2 50 pF Open Closed <sup>t</sup>PZH 1  $k\Omega$ or ten Closed **tPZL** 150 pF Open Open Closed **tPHZ** 50 pF  $1 k\Omega$ tdis Closed Open **tPLZ** 50 pF or Open Open tpd or tt 150 pF





VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 6 \ ns$ ,  $t_f = 6 \ ns$ .
- D. For clock inputs, f<sub>max</sub> is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tpzL and tpzH are the same as ten.
- H. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms





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### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC646DWR	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC646	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC646DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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### \*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74HC646DWR	SOIC	DW	24	2000	350.0	350.0	43.0

DW (R-PDSO-G24)

### PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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